



Material Content Data Sheet



Sales Product Name				IPD036N04L G		Issued		26. August 2018	
MA#				MA001662060					
Package				PG-TO252-3-311		Weight*		314.20 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.247	0.72	0.72	7151	7151	
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137		
	non noble metal	iron	7439-89-6	0.143	0.05		456		
	non noble metal	copper	7440-50-8	143.098	45.54	45.60	455437	456030	
	non noble metal	aluminium	7429-90-5	3.668	1.17	1.17	11676	11676	
wire	inorganic material	antimonytrioxide	1309-64-4	1.957	0.62		6230		
encapsulation	plastics	brominated resin	-	2.097	0.67		6675		
	organic material	carbon black	1333-86-4	2.237	0.71		7120		
	plastics	epoxy resin	-	18.875	6.01		60075		
	inorganic material	silicondioxide	60676-86-0	114.651	36.49	44.50	364899	444999	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11903	11903	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	275	276	
solder	non noble metal	tin	7440-31-5	0.043	0.01		137		
	noble metal	silver	7440-22-4	0.054	0.02		171		
	non noble metal	lead	7439-92-1	2.056	0.65	0.68	6542	6850	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		61		
	non noble metal	copper	7440-50-8	19.177	6.10	6.11	61036	61115	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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